










Board Stack Report

Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Paste			
2		Top Overlay	Tin Plating	0.005mm	
3		Top Solder	Solder Resist	0.010mm	3.5
4		Top Layer	Copper	0.036mm	
5		Dielectric 1	FR-4	0.320mm	4.8
6		Bottom Layer	Copper	0.036mm	
7		Bottom Solder	Solder Resist	0.010mm	3.5
8		Bottom Overlay	Tin Plating	0.005mm	
9		Bottom Paste			
	Height : 0.411mm				